ATLAS Phase-II Strip Tracker Upgrade

ABC130 ASIC Total Ionizing Dose Testing

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Outline

- Insufficiency of current inner detector in HL environment
- ATLAS phase-II semiconductor tracker upgrade
- Total Ionizing Dose (TID) effects of radiation
- Testing details & results



Current ID

Insertable b-layer - IBL (added in long shutdown 1):

supporting high resolution pixel detector, b-jet tagging

Pixel detector:

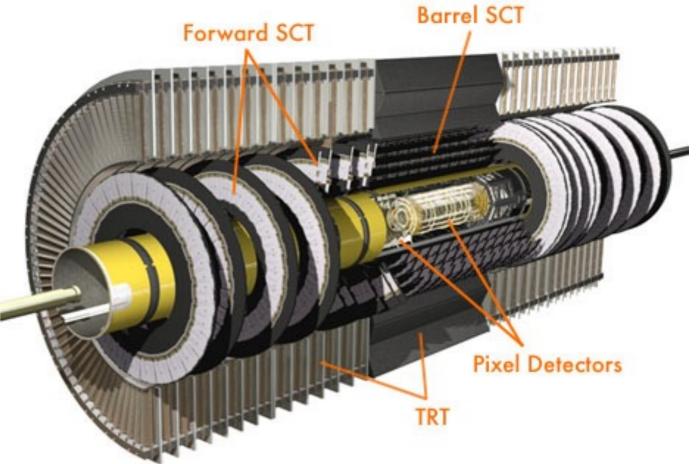
- high resolution vertex reconstruction and impact parameter measurements
- r=5-9 cm, 80 million pixels

Semiconductor tracker - SCT:

- momentum measurement
- r=30 -52 cm + end caps

Transition radiation tracker - TRT:

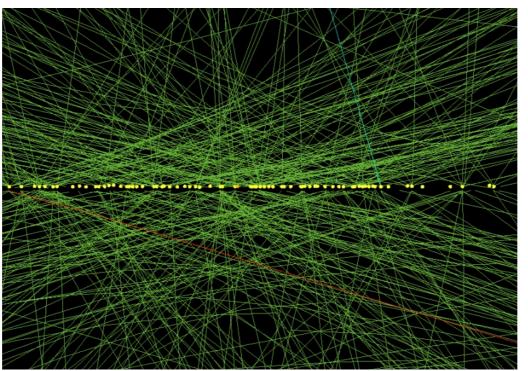
- particle tracking & electron identification
- straw tubes cover r=56-107 cm + end caps

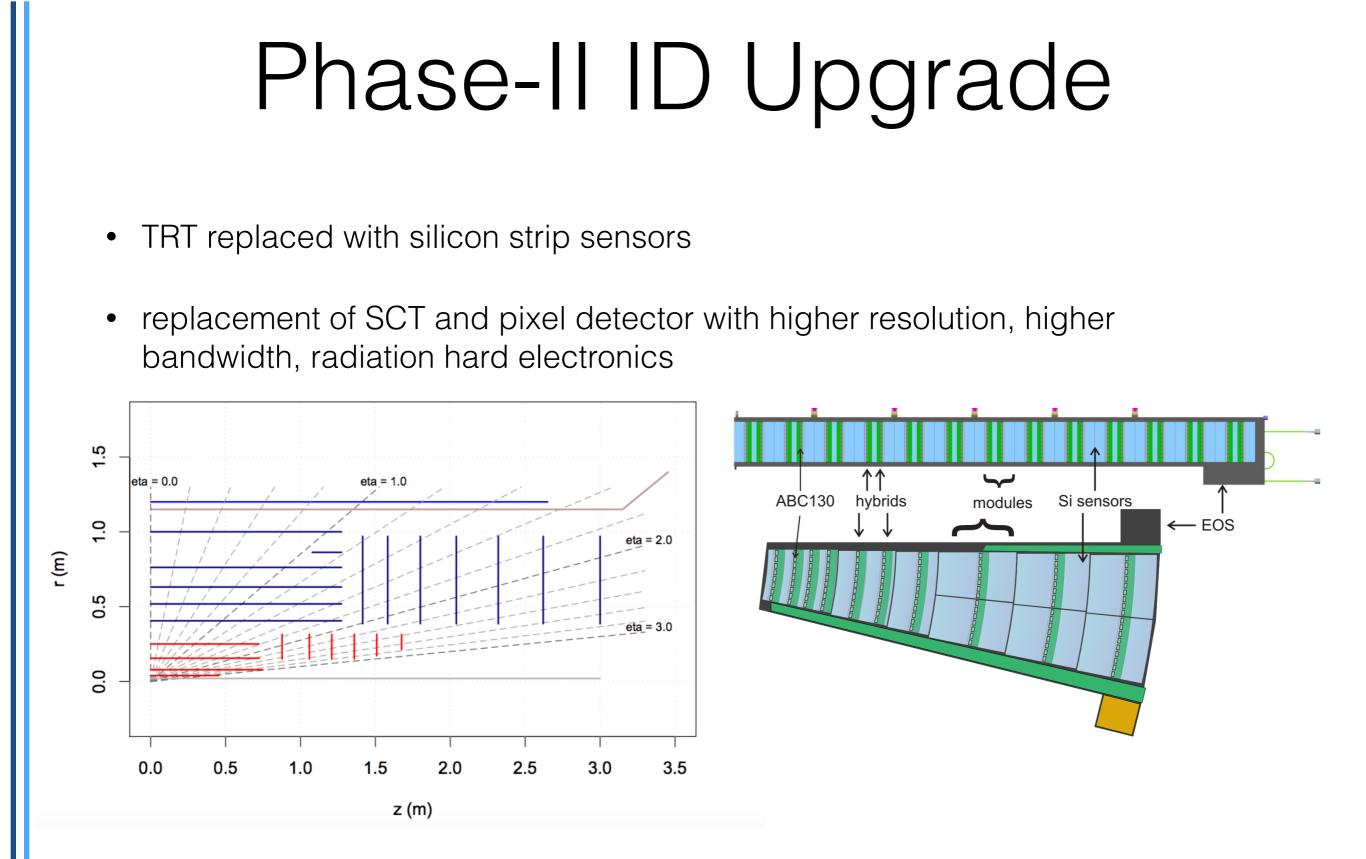


Failure at High Luminosity

- 3000 fb⁻¹ of integrated luminosity over 10 years to be accumulated at HL-LHC is 10 times what the current ID was built to endure
- luminosity of $\mathcal{L} = 5 \times 10^{34} cm^{-2} s^{-1}$ result in nearly 100% occupancy of TRT straw tubes and will surpass the capability of the SCT (Si strips) to resolve nearby particles
- higher granularity and more silicon strip detectors are needed to resolve pileup of ~140 vertices per event

Conclusion: high performance requirements for the HL-LHC cannot be met by current ID





 \star barrel \rightarrow stave \rightarrow module \rightarrow chips & strips

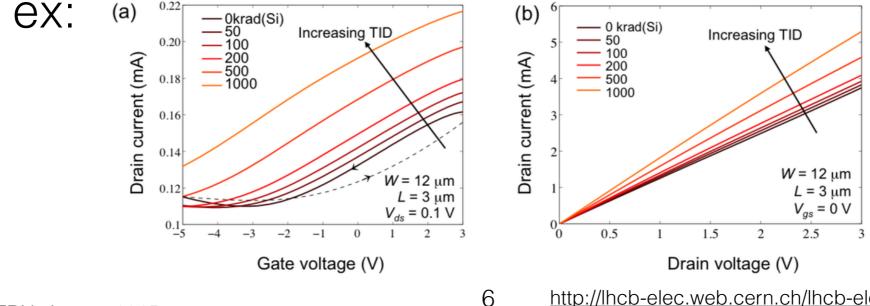
TID Effects of Radiation

Total lonizing Dose: effects & damage caused by total amount of ionizing energy deposited in the material of the device (contrary to Single Event Effects)

causes buildup of charge in material:

- SiO₂ electron hole pairs do not recombine quickly, in an E field electron & hole drift
- electrons are more mobile and dissipate, holes get trapped at defect centres and at ٠ Si-SiO₂ interface
- buildup of charge changes operating characteristics, causes leakage current and • changes threshold voltage of transistors

 \star expect leakage current from the chip's digital & analog architecture to increase with dose

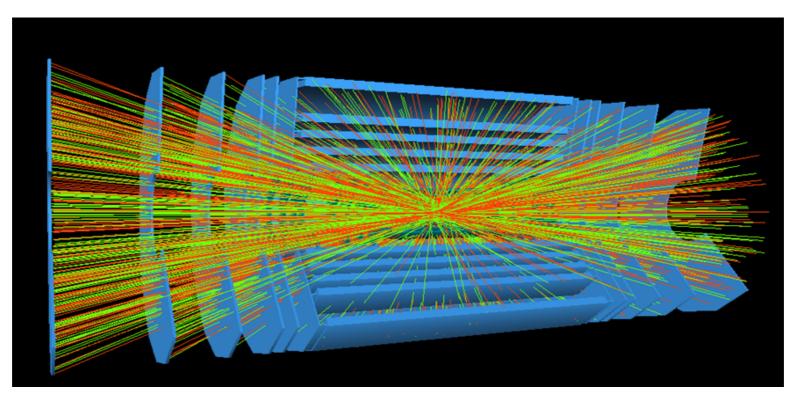


A. Morningstar, CERN, August 2015

http://lhcb-elec.web.cern.ch/lhcb-elec/papers/radiation tutorial.pdf

Radiation Tolerance

- increased current to ABC130s across entire detector can cause cooling and power supply issues
- must have a consistent threshold voltage across channels for reliable strip readout and accurate measurements
- expect ~30 Mrad = 300 kGy = 300 J/g over lifetime of ABC130 use in SCT

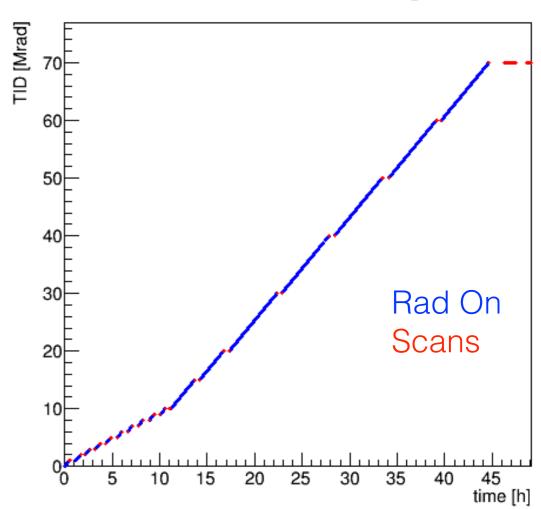


TID Procedure (1)

- constant dose rate 2 Mrad/h
- room temperature (cooling system was not available)
- exercised chip during irradiation
- 30 minute pause for scans each step
- measured I&V from power supply and V across chip throughout entire procedure

TID Delivery Scheme

Dose Range [Mrad]	Dose Step [Mrad]
0-10	1
10-20	5
20-70	10



ABC130 TID Testing

TID Procedure (2)

efficiency

an [mV]

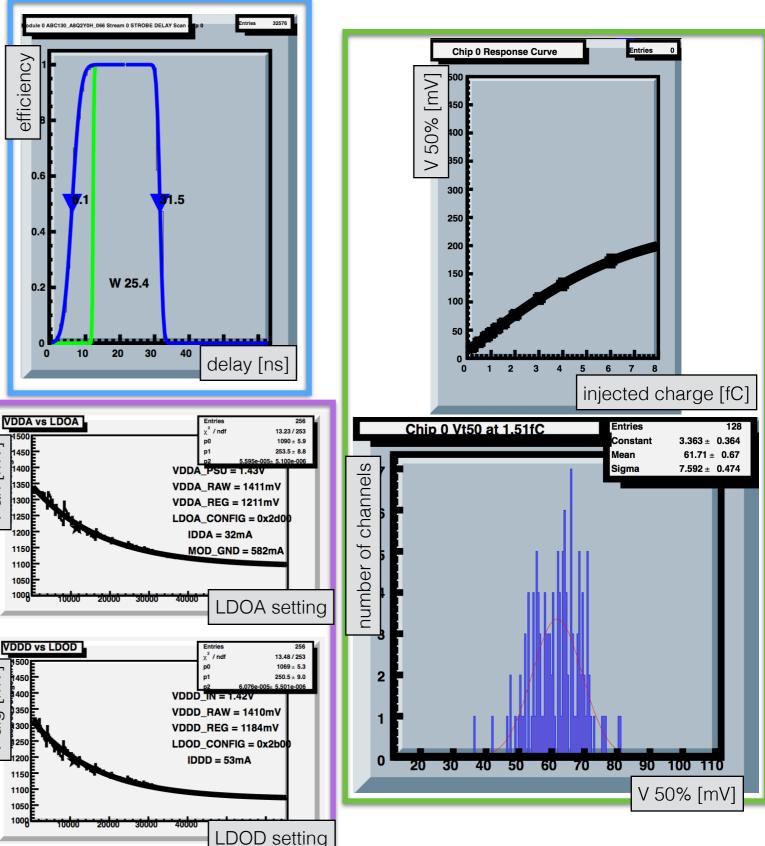
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V dig [mV]

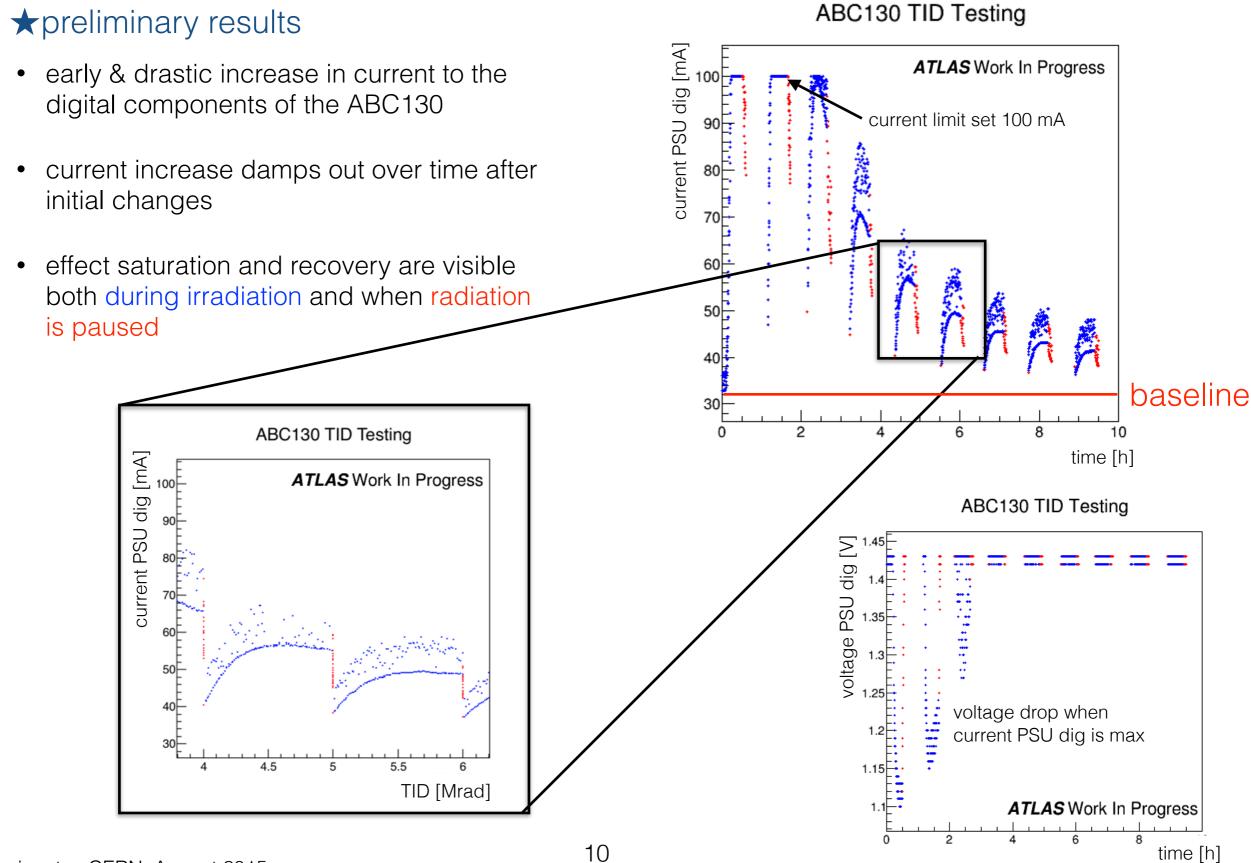
1100

scans performed at each step:

- strobe delay: calibrates delay time between test charge injection and channel readout
- response curve: measures 50% threshold voltage over injected charge, gain (mV/ fC) for each channel, voltage offset V(0 fC)
- scan ADC's: sets analog to digital converters to match nominal operating voltages



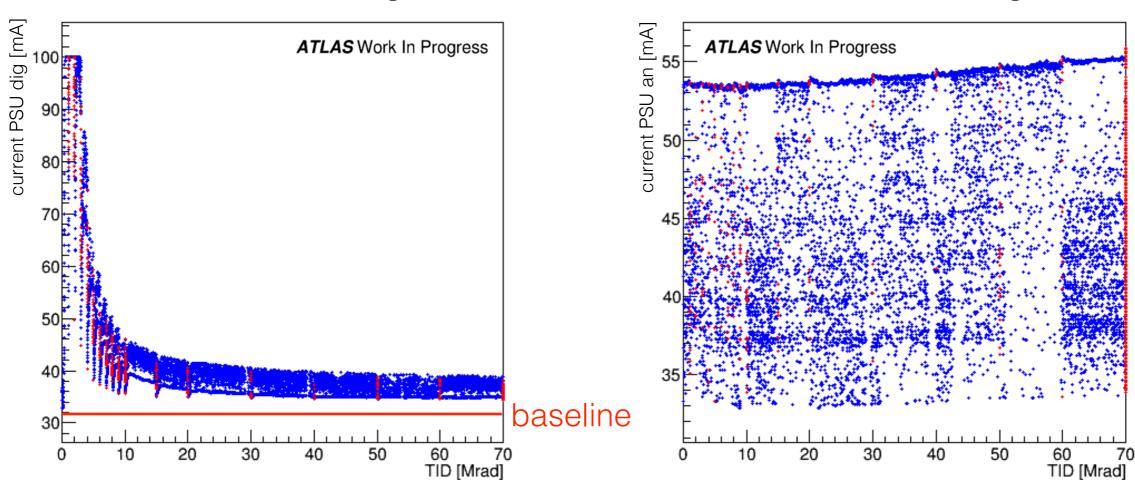
Results (1)



Results (2)

★preliminary results

- over full 70 Mrad effects diminish
- no extreme effects on analog part of the ABC130



ABC130 TID Testing

ABC130 TID Testing

*dependences to be explored: temperature, dose rate, radiation type

Summary

- large effect within first few Mrads
- ABC130 ASIC retained full functionality throughout & after 70 Mrad
- recovery observed throughout irradiation and pauses
- still preliminary, needs to be tested with lower dose rate and temperature (253 K)







